

SINTEC

SOFT INTELLIGENCE EPIDERMAL COMMUNICATION PLATFORM

www.sintec-project.eu



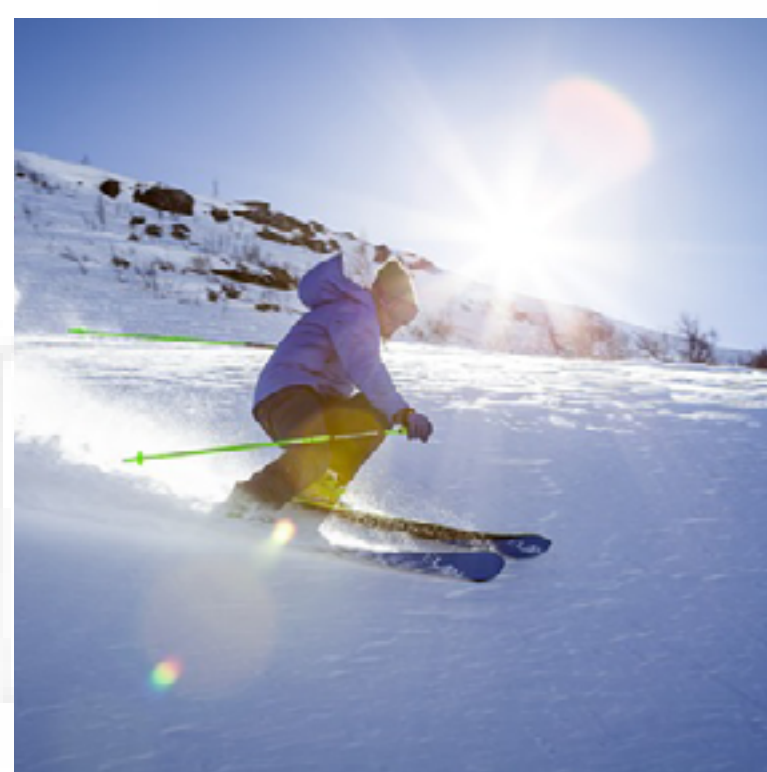
THE PROJECT

SINTEC is a Horizon 2020 funded project that will provide **soft, sticky and stretchable sensor patches** that can be used multiple times and at longer periods. With its dynamic compliance and water repellent permeable encapsulation it withstands vigorous action, sweating and water; making it **ideal for an active life**.

Our vision of extensible smart patches is a **non-invasive support system** that can be used all the time, allowing an active elderly person to be warned when their **health is slowly deteriorating** (for example in case of heart or muscle problems) or to help a person **recovering in a faster rehabilitation** with sensory support and recommendations from an app without having to be in a physiotherapy institute for too long (eg. after a long illness, stroke or trauma).

The main advantages should be in **comfort** and that the sensors do not move so much relative to the skin. Hence, its major impact will not be in replacing other wearables but rather **providing novel capability**.

To demonstrate the advantages of the novel technology, SINTEC will apply it in **clinical environment and in athletics performance evaluation**.



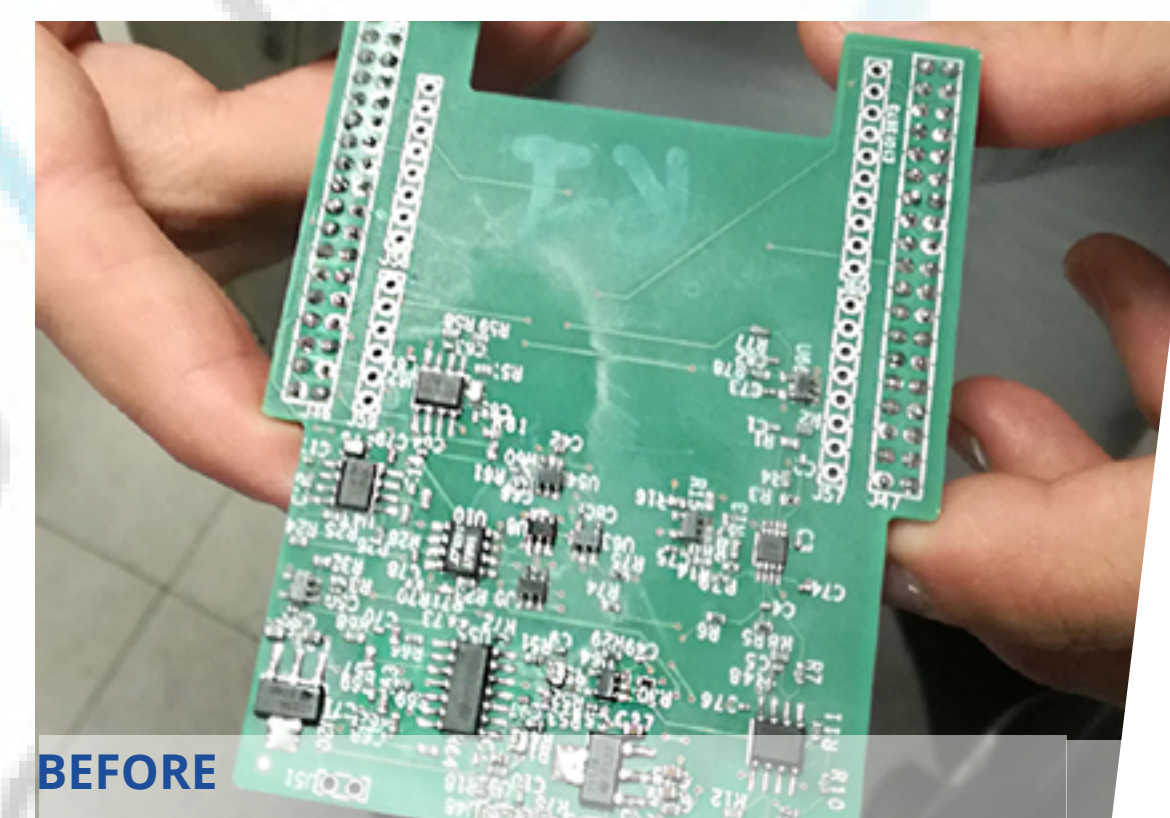
THE TECHNOLOGY

The aim of SINTEC is to advance a **rigid-stretch PCB technology with stretchable substrate and liquid alloy**, and to demonstrate its usability in complex applications, involving wearable sensing, embedded processing, and Fat-IBC. This will substantiate the advantages with this rigid-stretch technology and its improvement area. Industrial manufacturability and cost/scaling issues will be investigated.

Its unique features will enable a ground breaking **intra body communication** technique that provides secure communication at large bandwidth and low power, allowing for multiplex sensoric inputs from many sensor nodes on the body.

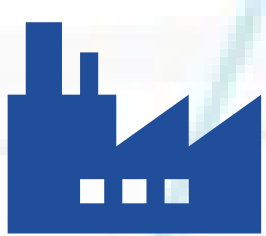
SINTEC MAIN OBJECTIVES ARE:

- To demonstrate manufacturing of large area rigid-stretch PCB technology stretchable substrate and liquid alloy interconnects;
- To demonstrate and compare the advantages of compliant and stretchable multi-use smart patches for Fat-IBC and low-energy Bluetooth communication;
- To demonstrate the advantages of compliant and stretchable multi-use smart patches for electrophysiological sensing;
- To validate the large area rigid-stretch PCB integration technology in laboratory.



EXPECTED RESULTS

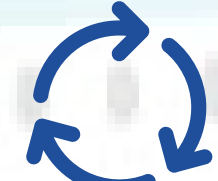
1. Manufacturing large-area rigid-stretch PCB



To make a ground-breaking novel large-area rigid-stretch PCB technology available for manufacturing on an industrial scale



To present long stretchable wireless sensor patches that survives multiple-use, and excessive dynamic stretching without contact failure



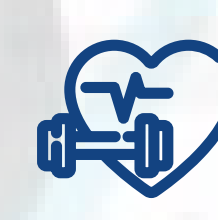
To make an assembly protocol that allows for recycling of batteries and reuse of more expensive components

2. Integrating Fat-IBC with electrophysiological sensors



We propose the communication through the fat tissue, which offers **lower losses for microwave propagation** compared to other tissues. We have previously demonstrated the feasibility of using fat tissue as a low loss microwave transmission channel for IBC and we have demonstrated successful communication scenario, where real data has been transferred through Fat-IBC.

3. Device demonstration in sports and healthcare



The novel SINTEC technology will greatly increase the usability of measuring methods, especially for reasons such as:

- being **less disturbing for athletes** compared to existing technology;
- enable **better compliance and adhesion to the human body** and can handle an intense elite sports, an activity that results in large amounts of sweating;
- enable **use in cold winter outdoor environment** (-15 °C);
- from the user perspective, the newly developed technology will be equipped with an intuitive and **easy-to-use user interface**.

DETAILS

PROJECT TITLE: Soft Intelligence Epidermal Communication Platform

ACRONYM: SINTEC

STARTING DATE: 01 January 2019

ENDING DATE: 31 December 2022

CALL IDENTIFIER: H2020-ICT-2018-2

TOPIC: ICT-02-2018 | Flexible and Wearable Electronics

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PROJECT NUMBER: 824984

PARTNERS



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